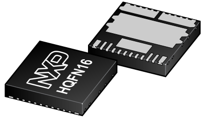

SOT1630-2

HQFN16, plastic, thermal enhanced quad flat package, no leads; 16 terminals; 0.9 mm pitch; 12 mm x 12 mm x 2.1 mm body

19 February 2019 | Package information

1 Package summary

Terminal position code Q (quad)

Package type descriptive code HQFN16

Package style descriptive code HQFN (thermal enhanced quad flatpack; no leads)

Package body material type P (plastic)

Mounting method type S (surface mount)

Issue date 22-05-2018

Manufacturer package code 98ASA00815D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	12	-	mm
package width	-	12	-	mm
package height	-	2.1	-	mm
nominal pitch	-	0.9	-	mm
actual quantity of termination	-	16	-	

2 Package outline

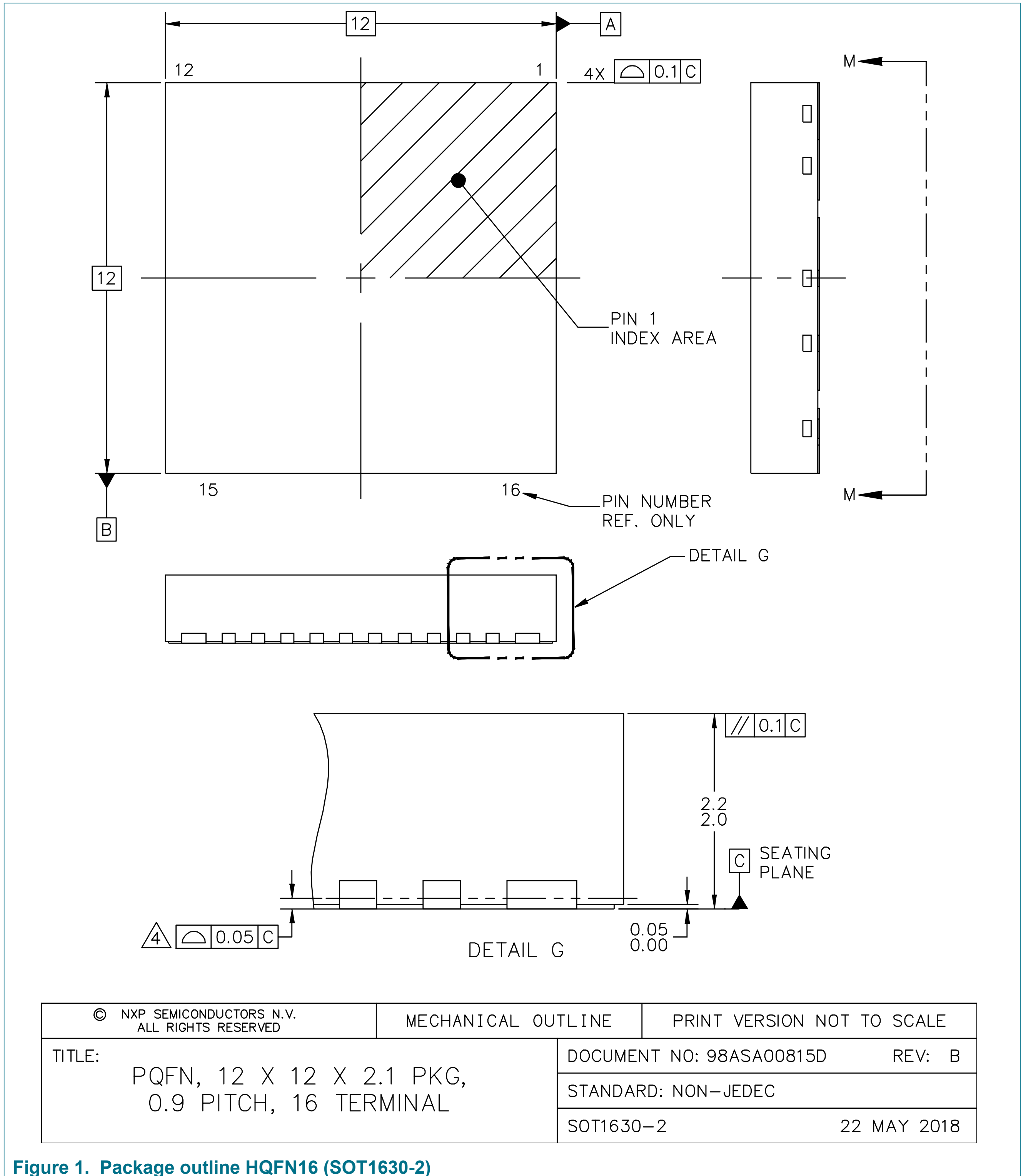

Figure 1. Package outline HQFN16 (SOT1630-2)

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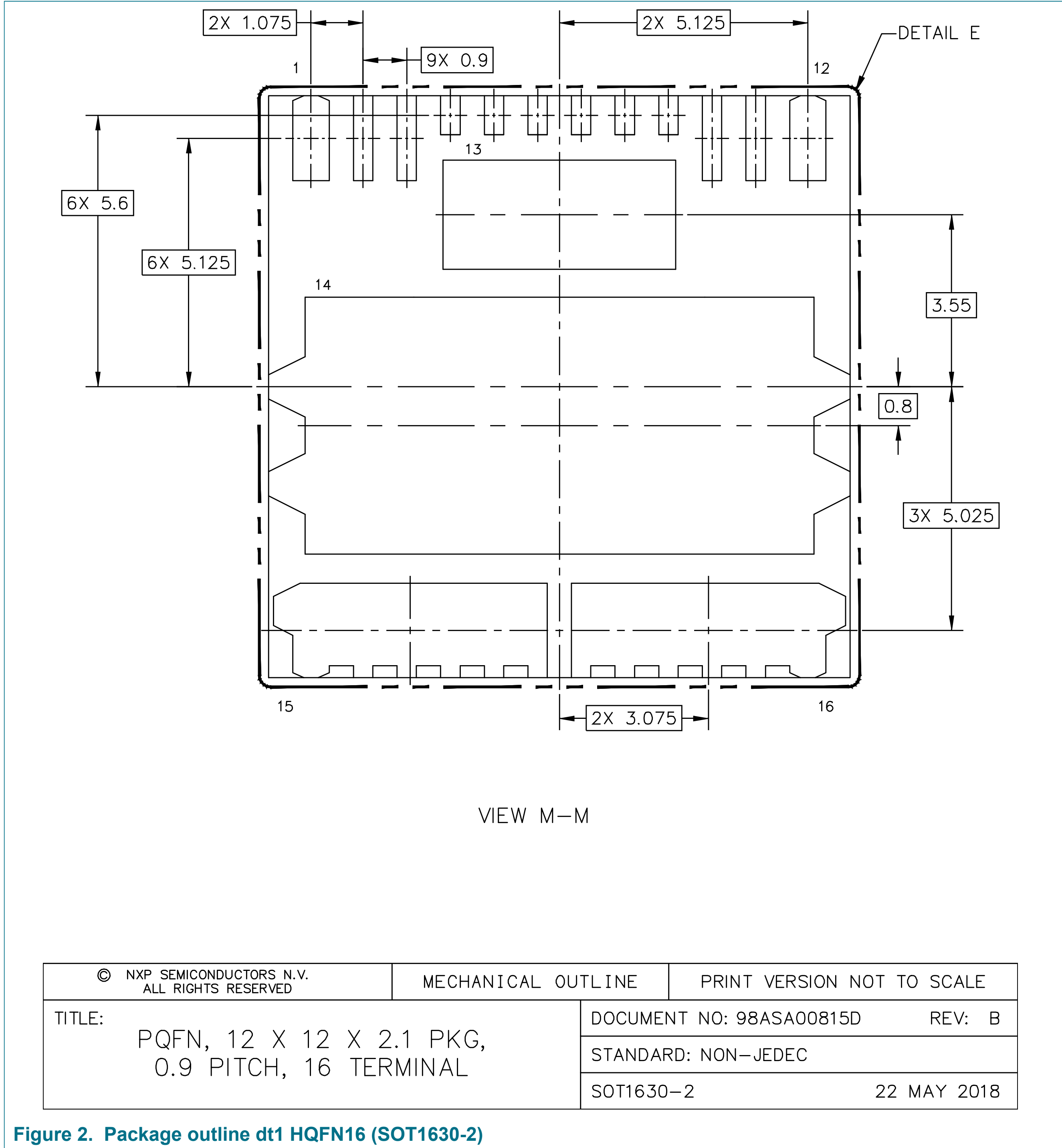

Figure 2. Package outline dt1 HQFN16 (SOT1630-2)

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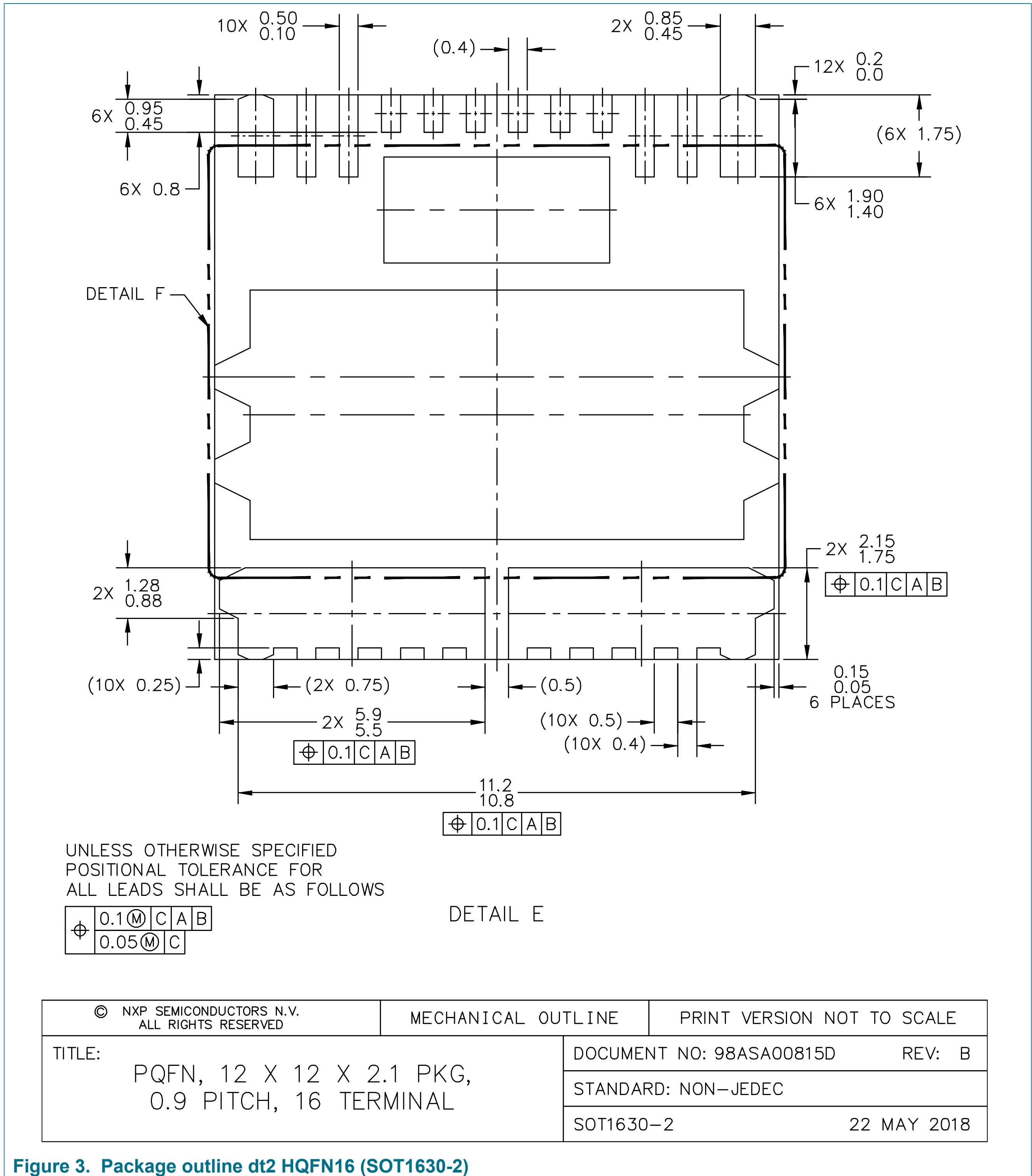

Figure 3. Package outline dt2 HQFN16 (SOT1630-2)

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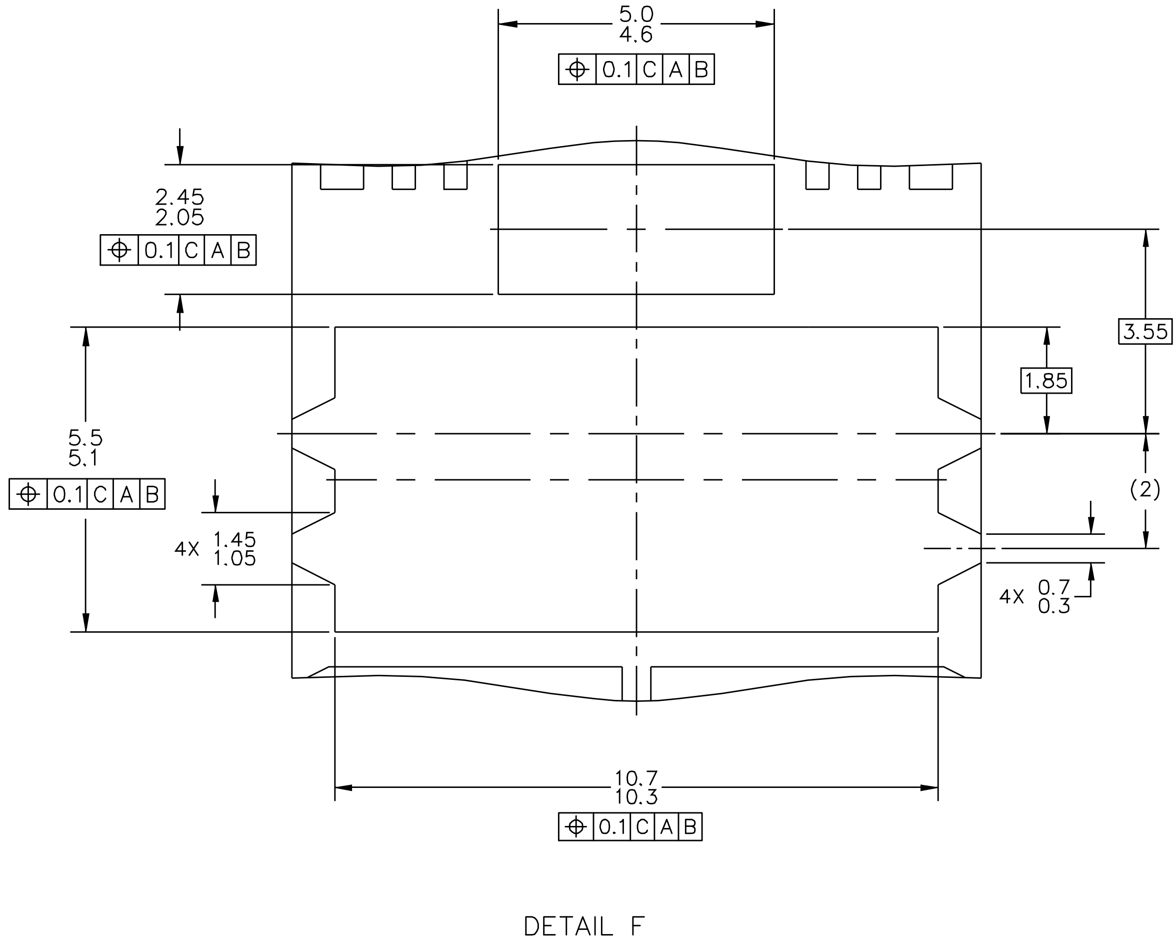

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	STANDARD: NON–JEDEC	
	SOT1630–2	22 MAY 2018

Figure 4. Package outline dt3 HQFN16 (SOT1630-2)

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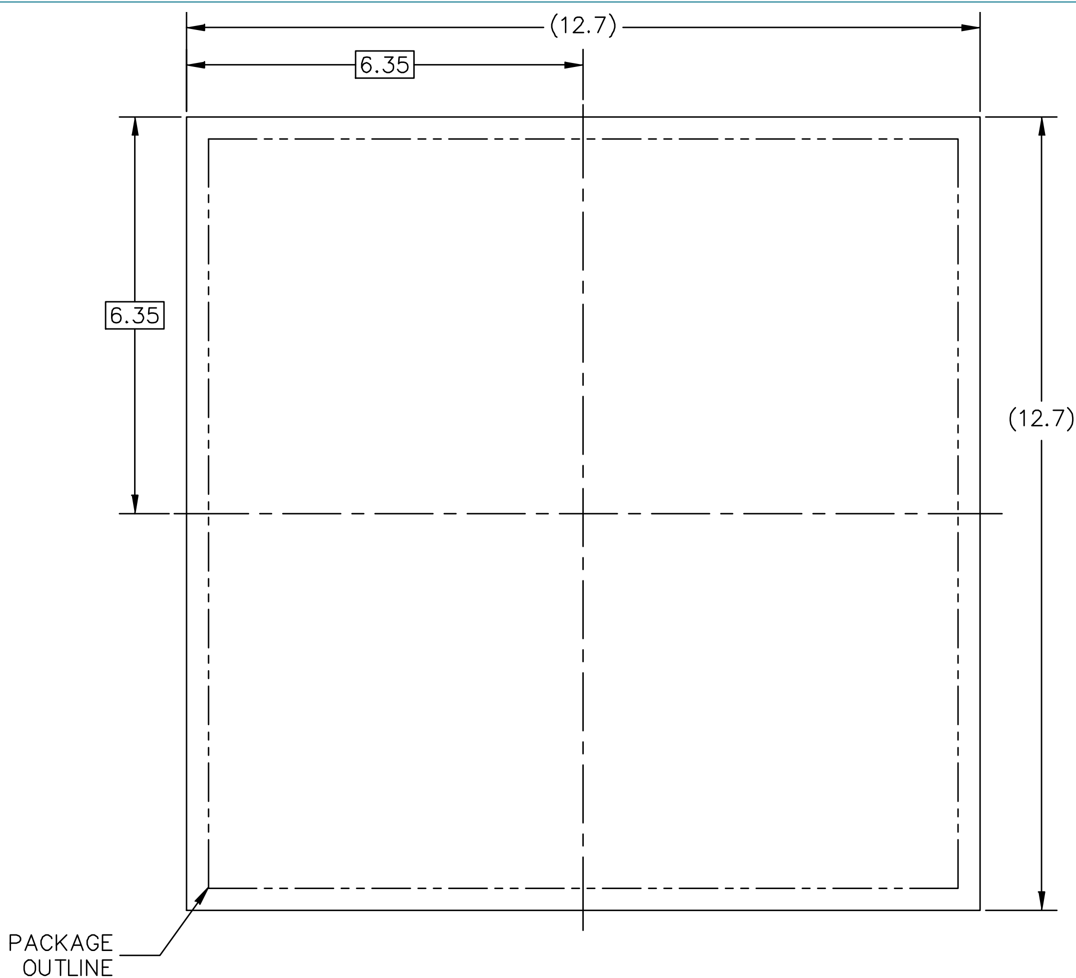
3 Soldering



PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN 1

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Figure 5. Reflow soldering footprint part1 for HQFN16 (SOT1630-2)

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PCB DESIGN GUIDELINES – SOLDER MASK OPENING PATTERN 2

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	SOT1630–2	22 MAY 2018

Figure 6. Reflow soldering footprint part2 for HQFN16 (SOT1630-2)

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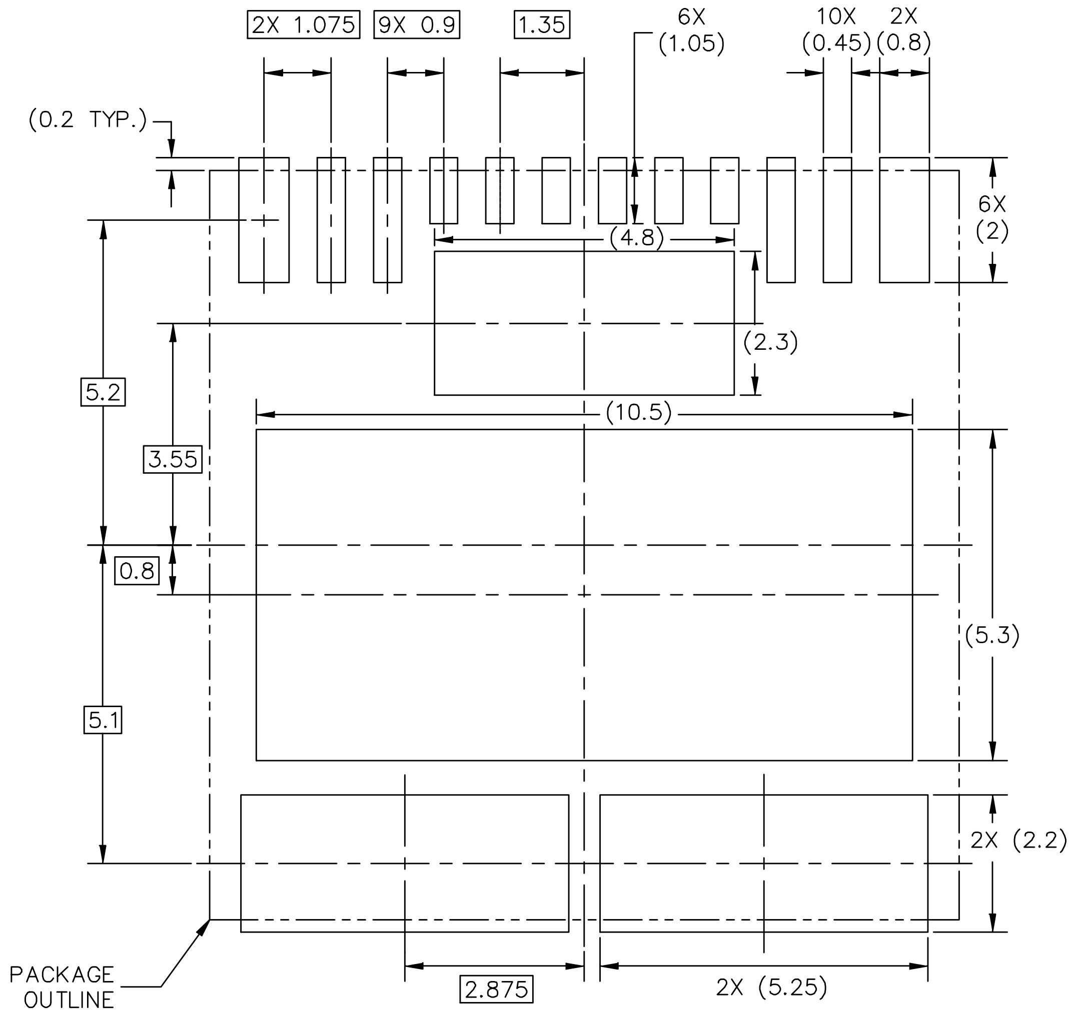

PCB CU GUIDELINES – I/O PADS & SOLDERABLE AREAS

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Figure 7. Reflow soldering footprint part3 for HQFN16 (SOT1630-2)

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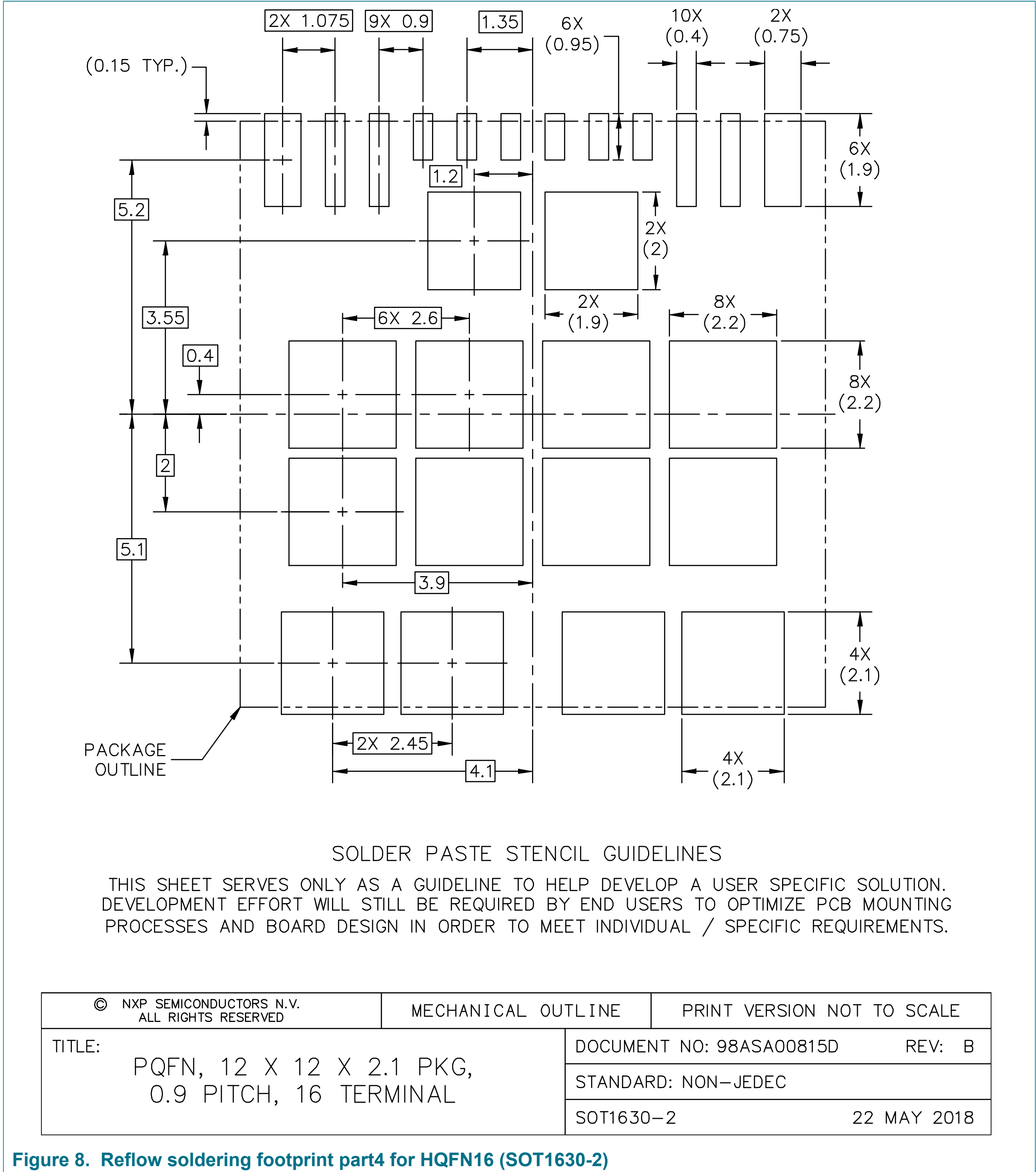

Figure 8. Reflow soldering footprint part4 for HQFN16 (SOT1630-2)

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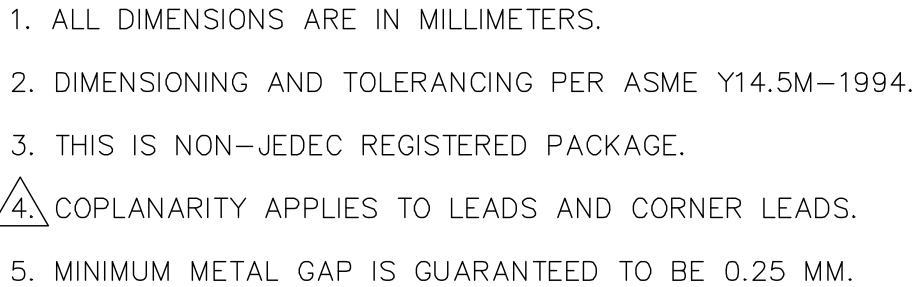

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	SOT1630—2	22 MAY 2018

Figure 9. Package outline note HQFN16 (SOT1630-2)

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4 Legal information

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Date of release: 19 February 2019